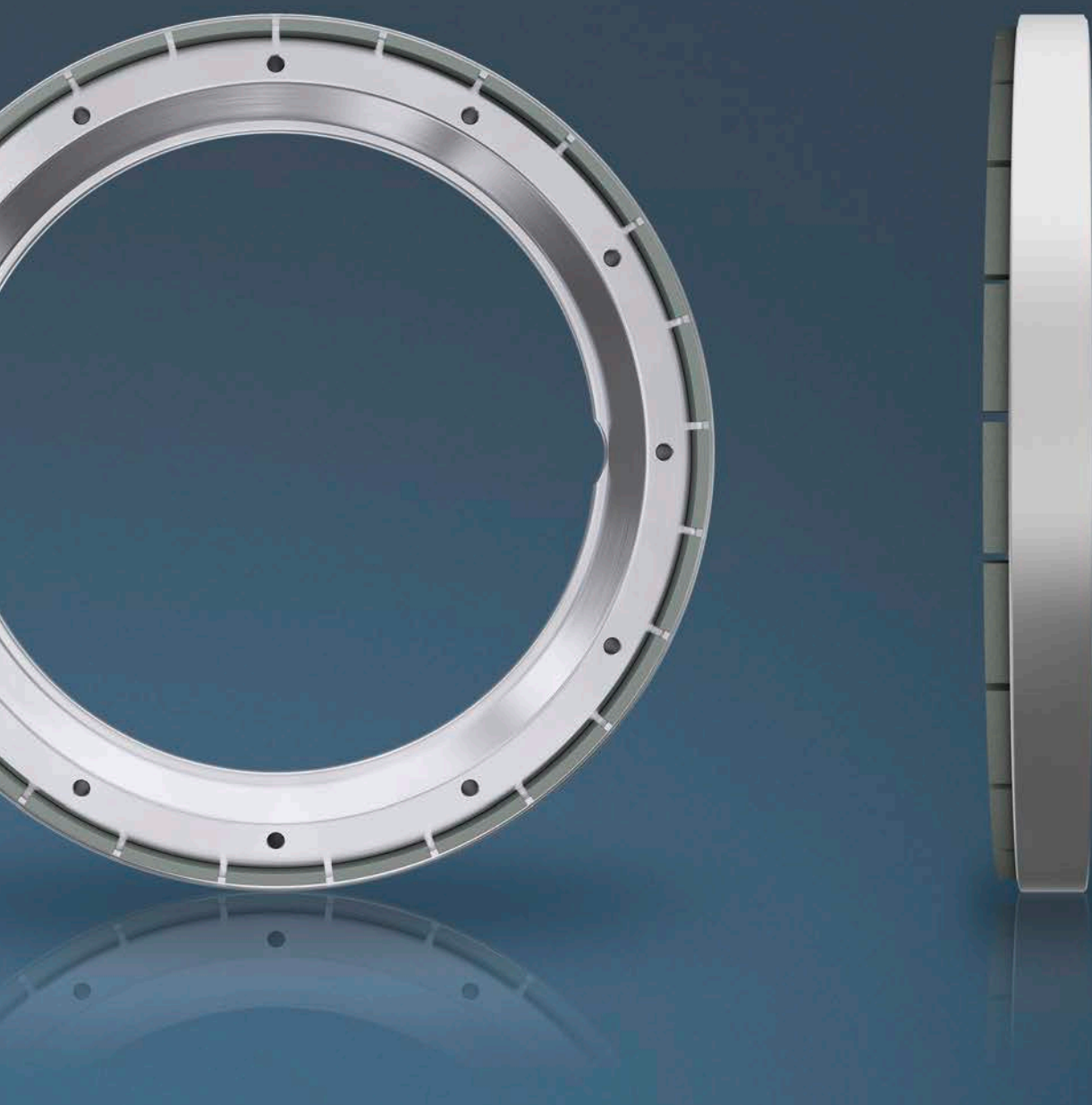




CENTURIA-E

Surface grinding wheels for the semiconductor industry

CENTURIA-E

The product assortment for surface grinding of wafers allows to reach highest quality surfaces with a significant improved die strength ratio. The composition of optimized diamond quality, special bond system and an unique core design produced with an innovative production technology at Asahi, guarantees lowest grinding forces during the grinding process. In combination with specific process adjustments an outstanding economic efficiency can be reached.

Application
Backgrinding of Wafers



+ Improved die strength ratio:
The combination of a grit size below 1 μ , optimized diamond quality with specific bond system and a special core design, allows to reach extremely high die strength ratios during the wafer production.

+ Stock range:
To ensure rapid availability, TYROLIT offers a comprehensive stock range of standard specifications.



+ Shorter grinding times:
The use of best diamond qualities embedded in a high performance bond system delivers higher stock removal rates and shorter grinding cycles.

Die strength ratio

TYROLIT Wafer surface grinding wheels reach a new level of die strength ratio.

TYROLIT	vitrified bond	up to 200%
STANDARD	resin bond	100%

High bond strength:
Optimized diamond quality in combination with the exceptional bond system allows to reach a cool grinding process which results in significant higher die strength ratio.

